

SUBMINIATURE SOLID STATE LAMP

PRELIMINARY SPEC

Part Number: AM2520SYCK09

Super Bright Yellow

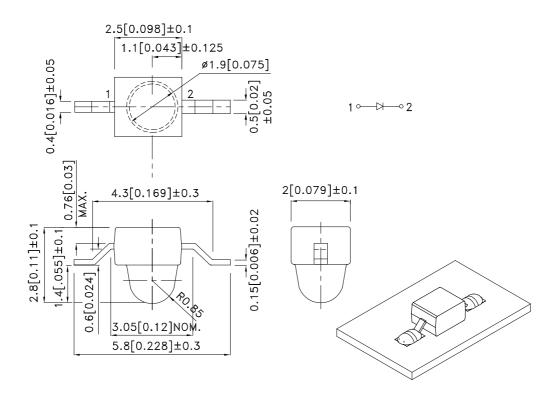
Features

- SUBMINIA TURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- PACKAGE: 1000PCS / REEL.
- RoHS COMPLIANT.

Description

The Super Bright Yellow device is made with DH InGaAlP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.

Pk



 SPEC NO: DSAD1289
 REV NO: V.5
 DATE: MAY/08/2007
 PAGE: 1 OF 5

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.L.LI
 ERP: 1202000720

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM2520SYCK09	Super Bright Yellow (InGaAIP)	WATER CLEAR	650	1300	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	IF=20mA
С	Capacitance	Super Bright Yellow	20		pF	V _F =0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	I=20mA
lr	Reverse Current	Super Bright Yellow		10	uA	V _R =5V

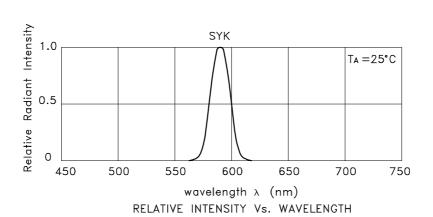
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

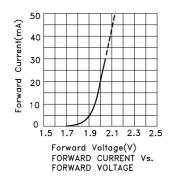
Parameter	Super Bright Yellow	Units				
Power dissipation	75	mW				
DC Forward Current	30	mA				
Peak Forward Current [1]	175	mA				
Reverse Voltage	5	V				
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

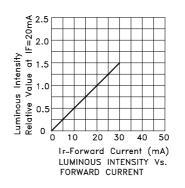
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

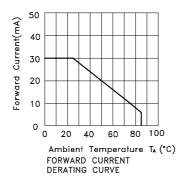
SPEC NO: DSAD1289 **REV NO: V.5** DATE: MAY/08/2007 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.L.LI ERP: 1202000720

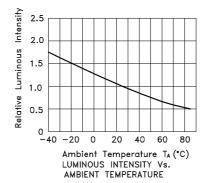


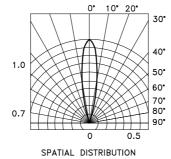
Super Bright Yellow AM2520SYCK09









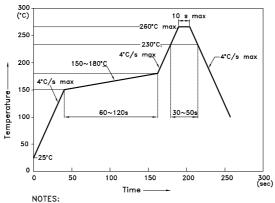


 SPEC NO: DSAD1289
 REV NO: V.5
 DATE: MAY/08/2007
 PAGE: 3 OF 5

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.L.LI
 ERP: 1202000720

AM2520SYCK09

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

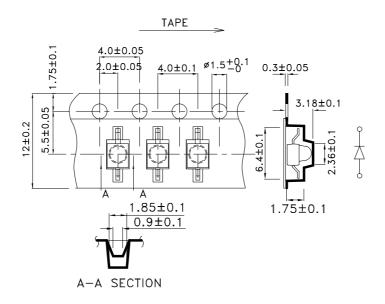
 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

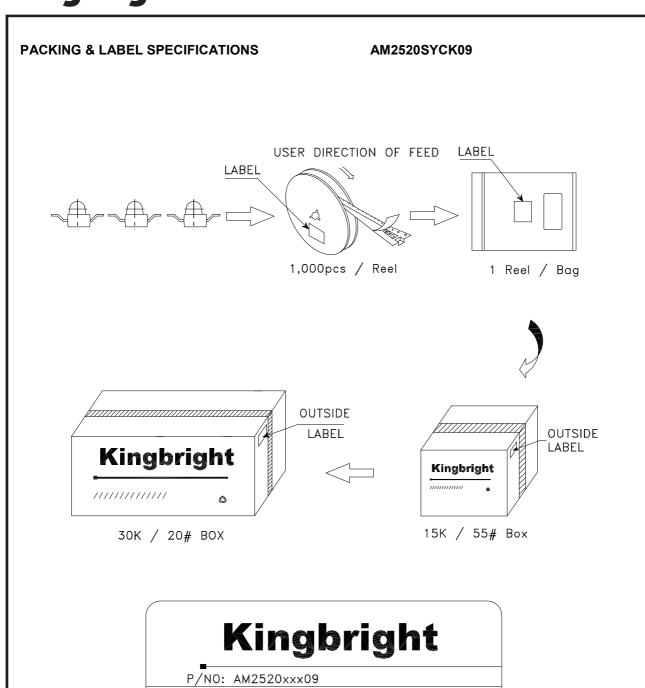
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

3.275 ø2 HOLE 1.5 1.5 6.55

Tape Specifications (Units: mm)



SPEC NO: DSAD1289 **REV NO: V.5 DATE: MAY/08/2007** PAGE: 4 OF 5 **APPROVED: WYNEC CHECKED: Allen Liu** DRAWN: Y.L.LI ERP: 1202000720





SPEC NO: DSAD1289
APPROVED: WYNEC

REV NO: V.5 CHECKED: Allen Liu DATE: MAY/08/2007 DRAWN: Y.L.LI PAGE: 5 OF 5 ERP: 1202000720